

MULTILAYER PRINTED CIRCUIT BOARD

ABSTRACT OF THE DISCLOSURE

A multilayer printed circuit board comprises a core substrate, multilayer wiring layers formed on the substrate by alternately laminating an interlaminar insulating layer and conductor circuit, and a group of solder pads having solder bumps planarly arranged on an outermost surface of the multilayer wiring layers, in which the solder pads located from first row to fifth row from an outer position of the solder pad group are constructed with flat pads connected to conductor pattern located on the outermost surface and solder bumps formed on the surfaces of the pads, while the solder pad group other than these solder pads are constructed with viaholes connected to flat innerlayer pad group located in an inner layer and solder bumps formed in recess portions of the viaholes, and the solder pads located from first row to fifth row from an outer position of the innerlayer pad group are constructed with flat pads connected to conductor patterns in the same layer as the innerlayer pad group, while the innerlayer pad groups other than the pads are constituted with flat pads connected to a further innerlayer flat pad group located inward the above innerlayer through viaholes.

FIGURE 1

This Sheet Has Been Replaced



THIS SHEET HAS BEEN
REPLACED